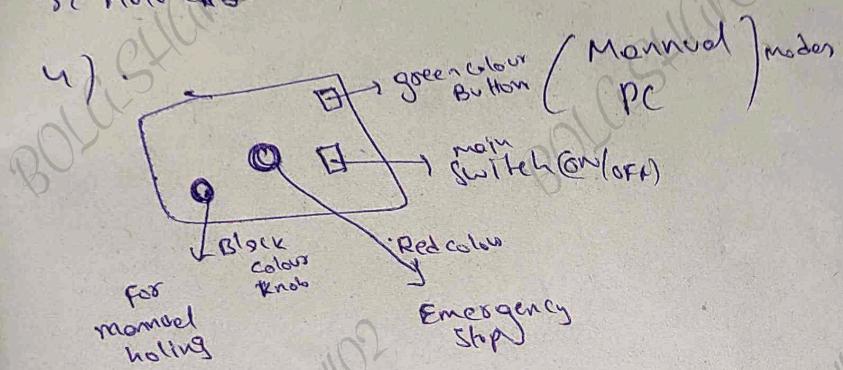


- 1) Acoustic bit
- 2) Hand held remote.
- 3) Auto chgck - cable



2)

tor is there

25000 RPM.

58 mm/sec

3500 m/min

0.0035 mm

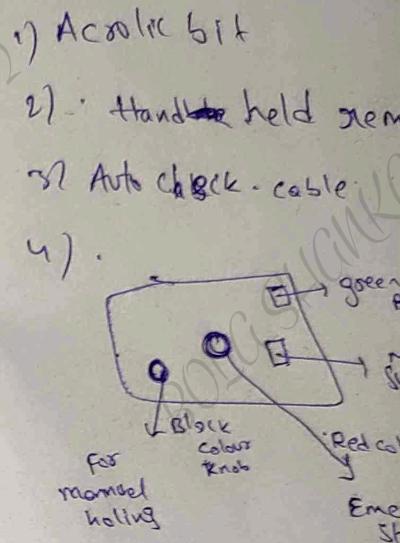
clean the copper plate

Machine Model

Machine specification

- 1) PCB Mate 300 Watt.
- 2) This is 3 axis machine (x, y, z)
- 3) Maximum working area
 - X-axis — 200mm
 - Y-axis — 300mm

It will be
- 4) Working for - two method
 - (i) Manual mode
 - (ii) PGI mode. (system mode)
- 5) Every axis individual stepper motor is there.
- 6) Spindle motor → BLDC motor.
 $x \& y$ axis. Rotation speed is 25000 RPM.
 working speed is 58 mm/sec
 3500 m/min
Machine resolution → 0.0035 mm



3

/ non linear

Mach - 3 mill

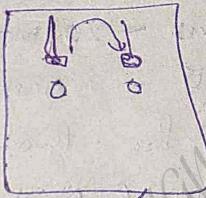
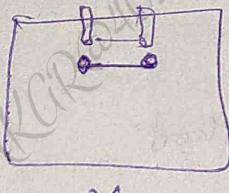
Machine process

1. Engraving
2. Maching
3. Drill
4. Cut

$$z = +2 \text{ season}$$

one drill completed and then

2 mm drill goes up and goes to
distance



Machine access area

X - 206 mm
Y - 300 mm

Copper Cad



Industrial tape



remove double sided tape.

Left
Side

13mm
Spanner

Right
Side

17mm
Spanner

30° 0.1MM
engraving bit
Red colour box.
Drill → Drill box
(white colour)
CUT → CUT box
(blue box)

Auto leveled

Software - 3

- clicking for copper cad is linear / non linear

Procedure
Linear G-Code

change
Mach-3 mill

- Bottom for G-code

↓
go to in ur circuit

↓
select engraving.txt file
click & open

↓
directly give to
create level g-codes

↓
AL.engraving.tab file
(text file → tab file).

Mach-3-mill

Software - 4

open → Reset-enable

i) off the reset button and

ii) give $x=0, y=0, z=2$

- File → load G-code

↓
take from ur folder

ALengraving File take

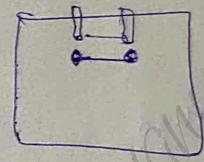
Machine process

1. Engraving
2. Masing
3. Drill
4. Cut

$z = +2$ season

one drill comp

2 mm drill g
distance



Copper Cad

↓

industrial tape

↓

remove da

• Left
Side

13mm
Spanner

Right
Side

17mm
Spanner

Machine → mill

↓
Drill (1.0) → click on

↓
Goo 22
Goo XOO YOO

↓
file → save as
saved in some location (Bridge Rectified)

↓
filename 1.0 DRILL

Machine → mill

↓
Drill (1.1) → click ok

↓
Goo 22
Goo XOO YOO

↓
file save as

↓
saved in Bridge Rectified

↓
filename 1.1 DRILL

Q tip Prophosh...
Q

now engraving select ok
 in program
 after G00 Z2 line
 G00 Z2
 G00 X00 Y00
 now
 ↓
 G code generated
 circuit select ok
 G code
 save
 in the same file
 you have taken
 filename **ENGroogding**

• goto machine → mill
 ↓
 cut layer (on)
 ↓
 G00 Z2
 G00 X00 Y00
 ↓
 File → save as
 ↓
 saved in some location
 filename **CUT**

• machine → mill
 ↓
 Drill, (0.8) (click ok)
 ↓
 G00 Z2
 G00 X00 Y00
 ↓
 File → save as
 ↓
 saved in some location (bridge selection)
 ↓
 filename **0.8 DRILL**

• machine → mill
 ↓
 Drill
 ↓
 G00 Z2
 G00 X00 Y00
 ↓
 File →
 ↓
 saved in
 ↓
 filename

• machine → mill
 ↓
 Drill
 ↓
 G00 Z2
 G00 X00 Y00
 ↓
 File
 ↓
 save
 ↓
 filename

Step 4 Selected tool

→ goto parameters → selected tool

List of Drill
 (one page opened)
 only change
 List of DRILLS.
 • close before drills
 • select 0.8 drill
 • select 1.0 drill
 • select 1.6 drill
 ↓
 click OK.

Step 5 List of drill

→ goto machine → list of drill
 → just for matched or not matched checking purpose.

Step 6 Contour

→ goto machine → contours

↓ calculate contour

give OK

(it gives final prototype board view)

(given board analyzing view)

Step 7 G-code generation.

→ goto machine → Mill → select Mill → shows one pop up

↓ output file

selected only

Section #1

output
 Section #1

Any circuit engineering & circuit & drill
 (0.8 / 1.0 / 1.6)

identical pad
 sets 0.8
 .6 size
 to 1.6.

list of drill

identical pad

1.1
 1.02

operations
 2 drill (1)

Step 3

List of Drill checking

→ goto Machine → last option
List of Drill (Now it will show)
list of drills

Diameter	No.
0.81	1
1.02	2
1.12	3

(Notes) Resistor
capacitors

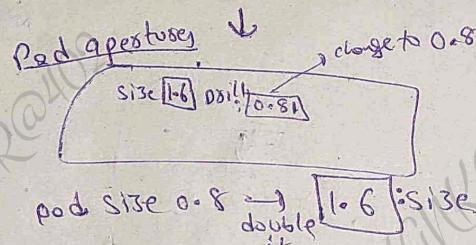
* Not available p. 81 drill bit

• 0.81 → Any drill → Right click

(0.8) (select one
drill)

edit all identical
pad

for circular
soldering
process



Matched for checking. Size changed to 1.6.
not matched goto Machine → List of Drill

• 1.12 → Any one drill → Right click

(1.1)

edit all identical pad

Pad Aperture

size [1.2] drill [1.02]

for oval
shape soldering

→ first x change to define as pad
1.02 → Right click

Some process like circular

1.02 → 1.00

Pad Aperture
size [2] drill [1]

Step 4

Selected to

→ goto parameters →

Step 5

List of D

→ goto machine → list of dr
⇒ just for mat

Step 6

Contour

→ goto machine → Cont

Step 7

G-code

→ goto machine → Mill

Any circ

→ Now drill & Select is matched.

Step ② Alignment process.

In this, we should align the circuit with the outline.

→ goto display → select Layer #6. (Black colour line changed to some other colour)

→ goto file → offset → coordinate offset
(Shift manually.)
No corner will change to hand set.
Now align according to circuit.

↓
click Reforge option
(Auto alignment)

→ goto display → select Layer 1. (Now circuit will be selected)

fixed predefined { Layer 5 → Drill layer
layer 6 → cut layer

→ goto file → select Filp horizontal (circuit changed to left to right)
(mirror image)

→ goto file → origin

y: 10 x: 10
click OK.

1. Goto File → open

Gerber loading Step 1

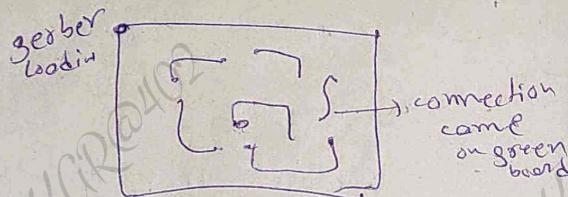
- New circuit

choose your done gerber file.

• if not shown → click select
 [All files]

- Select BOTTOM layer & open.

gerber load close
pad apatch close



- File → open → additional layers.

• select 'CUT layer'

open

→ dimension will be loading to select

give yes for ^{poston} Gerber tool

- File → open → Drill

select NCD file (open)

if incase Drill & circuit matches mean → Yes

not matched → No

① drilling & predefined (Select)

→ Now drill & select

Step 2 Alignment process

in this we have to outline

→ goto display → L

→ goto file → offset

→ goto display → layers

fixed & predefined { Layer 5 →
Layer 6 →

→ goto file → select

→ goto file → origin

x:[] y:[]
click

• Design completed

• Why will we generate Gerber

4. Software
 - 1. Eagle - deriving purpose
 - 2. Copper CAM
 - 3. Auto levels
 - 4. Mach-3 mil

Copper CAM → Gerber file $\xrightarrow{\text{converted}}$ (G-code
Software purpose)
Geobler file
 $(X, Y, Z - \text{axis})$

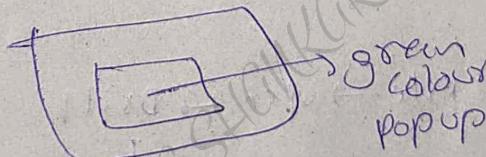
Why converted

↓
bcz machine understand G-code

• Copper CAM (7 steps)

1. Gerber loading
2. Alignment process
3. List of Drill
4. Selected Tool.
5. List of Drill
6. Contours
7. G-code generation.

Open Copper CAM



green
color
pop up

Section DRILL
 Device EXCELLON
 File XN.NCD

Layer → 44 Drills
45 Holes

DRILL | CUT | BOTTOM

→ Give/Click "process Job".

Before * in the saved folder
we have

LCK File → 2	SCH File
B#1 File.	Text document
B#1 "	
B#2 "	
BRD "	
S#1 "	
S#1 "	
S#2 "	
S#3 "	
S#4 "	

After clicking "process Job"

LCK File	NCD File
LCK "	S#1 File
B#1 "	S#2 File
BOTTOM "	SCH File
BRD "	Text document
CUT "	
DRI "	
GPR "	

• Design completed

• Why well we generate

copper CAM → gerber file
software purpose

gerber file
Bottom CUT Drill

• copper cam (7 st)

1. Gerber load
2. Alignment pr
3. List of Drill
4. Selected T
5. List of T
6. Contours
7. G-Code ge

open copper CA

PCB → Designing

→ Need to give titles.

u Scary

11 titles



first unselect all the layers (Right side)

section

delete

↓
BOTTOM

• Device [GERBER_RS274X]

• File.

% N. BOTTOM

case sensitive

• Right side Select layers → 16 Bottom
→ 17 Pads
→ 18 Vias

• click Add (do further operations).

Section

CUT

File

F.N. CUT

Layer →

Dimension 20

• Click Add

Step ③

Routing

goto Edit → collect Route

↓
1 top $\xrightarrow{\text{change to}}$ 16 bottom

→ select wire bend style 1

(track should connect 45°)

not 90°

flow of electrons will change suddenly
means lifetime of track
will be decreased

goto Edit → Rip Up → to change Routing
line

→ not use delete.

use without Routing do not go to
gerber generation

Step ④

Gerber Generation

goto file → CAM Processor

↓

one slide will open

PCB → design in

→ need to

first unselect all

• section *

↓

BOTT

• Device GEF

↓

• File %

↓

• Right Si

• click Add

• Section

file

Lay

• Click

PCB layout

1) Grid change ✓

2) Board dimension fixing

3) Components placement

4) Routing MS one track to some track some distance
blue small distance components No track should be drawn

② B Cato → Draw → Select dimension

16 Bottom → change to 20 dimension

Set 50

set 50 × 50 length of PCB board

goto Edit → Select

MOVE

→ change the outerline
to 50 × 50.
by clicking at the center
of the outerline you
can change the outerline

goto Edit → Delete

delete the dimensions values
showing (50)

→ click on 50
to delete

Step ③ B Board dimensions fixed
completed

Step ③ C Component placement

goto Edit → Select Move

Step - 2 Bill of material

open file "BR"

Select
Goto file → Run VLP

↓
Select bnm.vlp
↓
click open

Bill of material (opened)

↓
Save
↓

BR Save → close

Saves at txt document

→ it contains all the details of components

Goto File → switch to board → Yes

one pop-up slide will be opened.

③ A

Step - 3

View → Grid → Change inches to mm

size: 1 mm

Display On

Style Lines

Click OK

PCB layout

- 1) Grid changes
- 2) Board dimension fix
- 3) Components place
- 4) Routing ms one too blue sm

② B
Goto → Draw →
set 50

set 50 × 50

goto Edit →

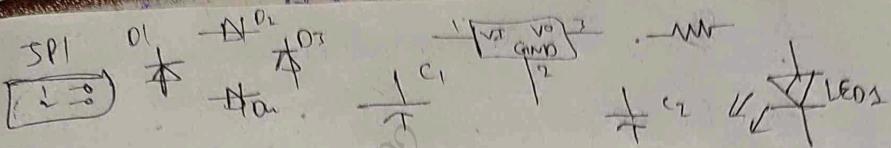
goto Edit → D

delete the dimension

Step ③ B Board completed

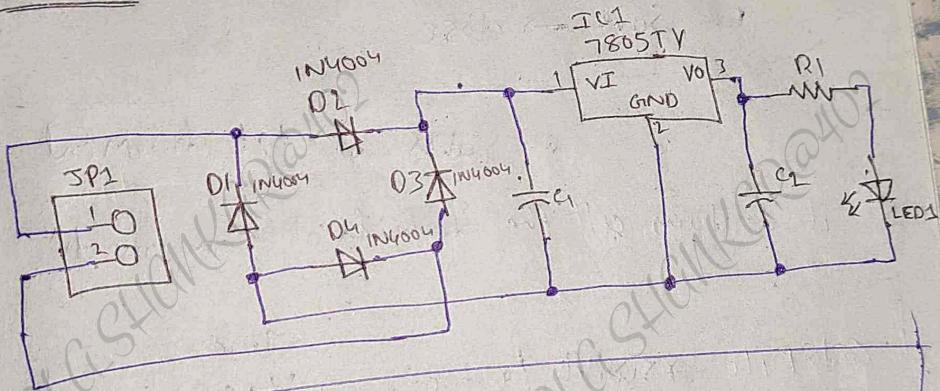
Step ③ C

goto Edit →



Goto - Draw → Net (choose)
connect the circuit

Connections



Goto Edit → Select
value

$$\begin{aligned}C_1 &\rightarrow 0.047 \mu F \\C_2 &\rightarrow 0.1 \mu F \\R_1 &\rightarrow 1K\end{aligned}$$

CTRL + S → Save the file "BR".

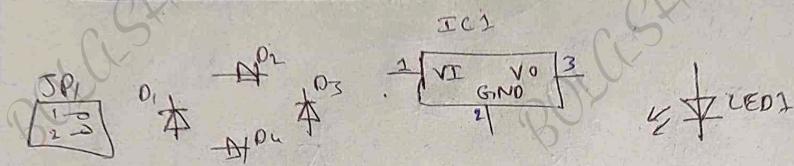
Edit → Add → Search (Led)

Selecting LED

LED 2AF = LEDs with 2 cathode & 2 Anod (chosen)

LED (choose)

LED5MM



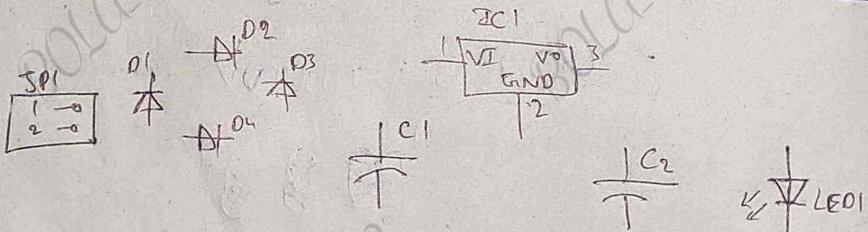
Edit → Add → Search (C)

E.

check "C" in alphabetical order

C-US .. Capacitors, American symbol (chosen)

C-U... (chosen) C025-024 X044



Edit → Add → Search (R)

R-US .. Resistors, American symbol (chosen)

R-U... 0207/10

ctrl

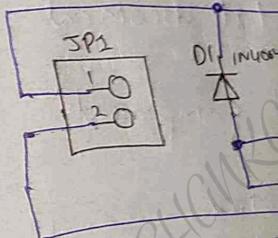
SPI

D0 D1 D2 D3 D4

Atan.

Goto - Draw → NE
connect

Connections



Goto Edit →

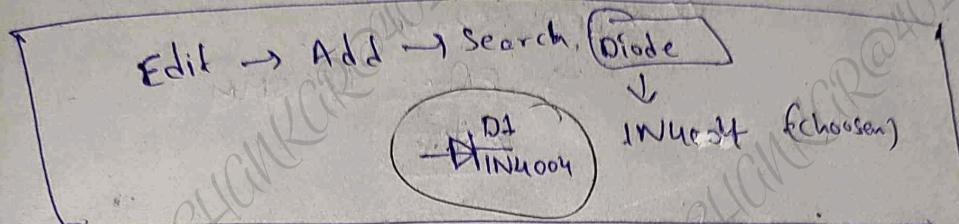
C1

C2

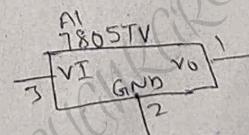
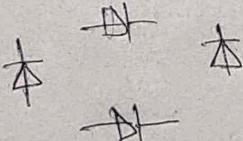
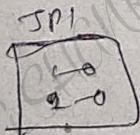
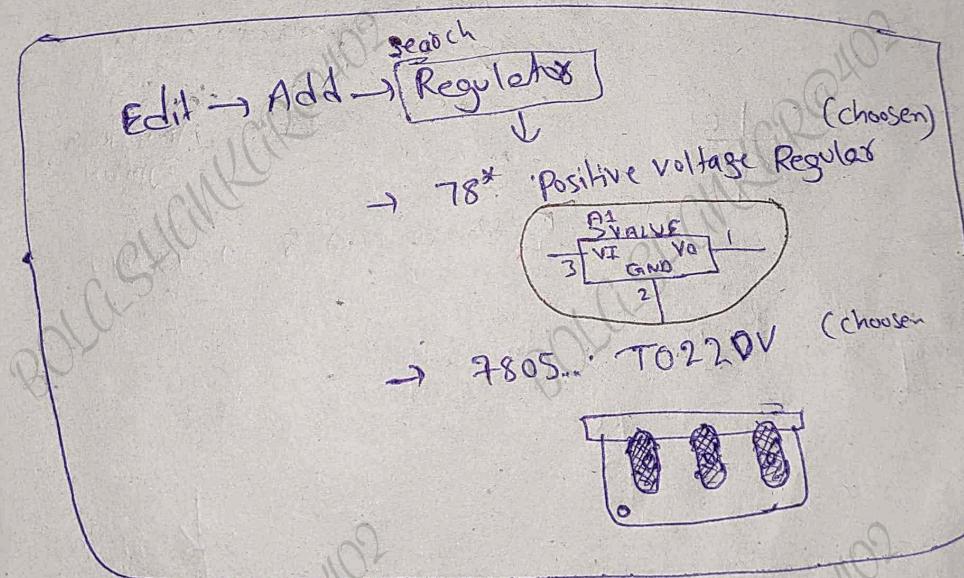
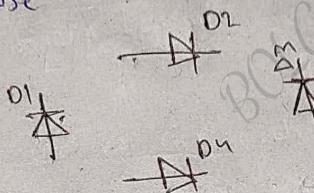
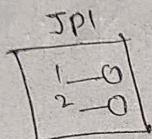
R

CTRL

Bridge rectifier used to blink the LED.
 (9V) (3.3V)
 (stepdown transformer) Resistor



ESC button house



EAGLE Software

4 Steps

1. Schematic
2. Bill of Material (BOM)
3. PCB ^{board} Layout design
4. Gerber generation

1. Schematic

Step: ①

- Goto File → New → schematic
- opens a schematic page

↑ we need to select grid opt.

- Goto View → Grid → Display On

Style @ Lines
size: 2 (0.01)
do not change values.
2.54mm
(inches → mm)

click OK

- Goto File → Save as "BR" name.

D:\402\Bridge Rectifier

- Goto Edit → Add option select
(this is the library page)

Search [Pin header]

click OK

(Red color)

Symbol → for schematic

Footprint → for PCB layout

(Green color)

→ Pin Header connector

→ Select 2 pin header

→ select "Pin 1x02".

A \$1
1-0
2-0
> Value



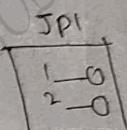
JPI

1-0
2-0

↓

Edit → Add

ESC button to use



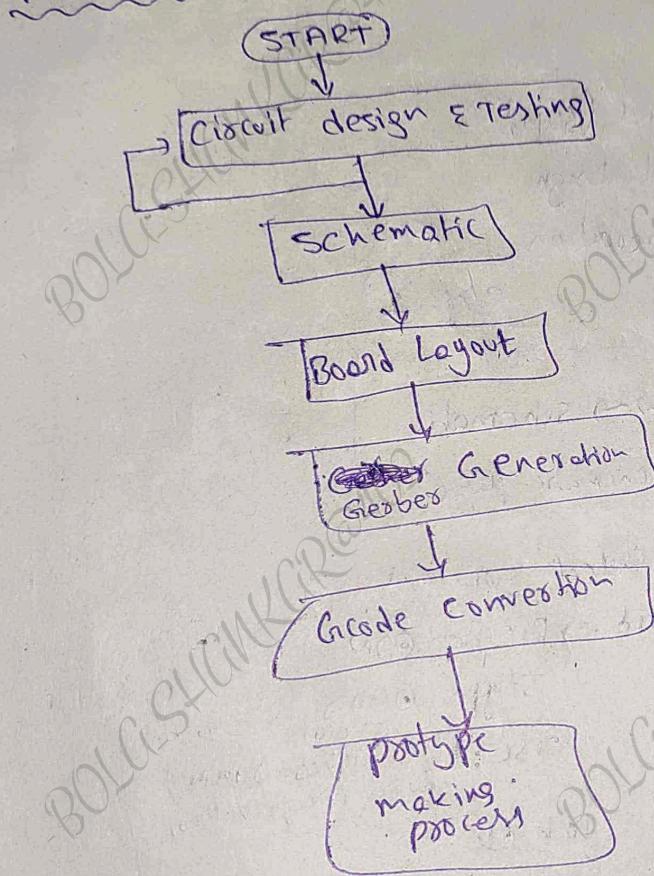
Edit → Add

JPI

1-0
2-0

↓

PCB Design flow:



Electronic Design Automation (EDA)

EDA Tools - (PCB design softwares)

- Protel / Altium Designer
 - Cadence - Orcad, Allegro
 - Mentor Graphics PADS
 - Zuken CADSTAR
 - Public - open source tools; Cadsoft Eagle
- } licensed
} ver

Protel is also PCB design software.

↳ simulation software

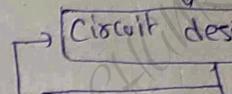
EAGLE → PCB software (not simulation).

PCB Design flow

Nxt two days → EAGLE & PCB design software

PCB Design flow

START



Schematic

Boards

Gerber

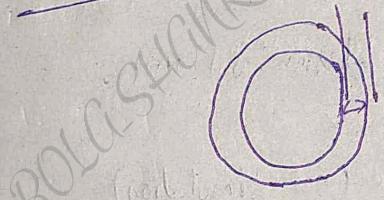
Ger

Ger

A & dino → blue colour solder masking
Raspberry pi → green colour

- Why colour different are used in PCBs.
 - Main reason to protect from oxidising
(main layer is copper layer)
 - : colour depends on customer appearance
 - Mostly green → track is very clear
(after 1(0) 2 year very clearly visible for tracks)

Annular Ring:



Bare Board:

With components, the board is Bare Board.

Track:
track width → depends on current consumption
depends on application - track width is designed.

Bill of Materials (BOM)

Types of PCB

- Single layer
- Double layers.
- Multi-layer (in layered)
 • PCB connections
- Rigid flex PCB
 • laptop (keyboard to screen)
 • maintain the life
 • old nokia flip phone Example
 • pop up camera
 • increase the life
- Aluminium PCB (absorbs heat)
 • Home appliances
 • LED Boards / LED panels

PCB Terminology.

FR-4

- copper thickness - 0.035 mm (top layer)

FR-4 copper plate

PCB Materials

types

FR1

Solder Masking

A & dots - blue colour
Raspberry pi - green colour

- Why colour
- Main reason to provide
 • main layer is colour
 • colour depends on
 • mostly green

Annular Ring:

Bare Board:

with component

TRACK:
track width
depends on

BILL OF M

Passive components
(e.g. resistors, capacitors, inductors, diodes, etc.)
are passive.
source/voltage
external source
voltage or current.

size of PCB ↓
complexity ↓
cost ↓

Passive component SMT

Passive two terminal component.

Package Type	Size in inches	Size in mm
0201	0.024" x 0.012"	0.6mm x 0.3mm
0402	0.04" x 0.02"	1.0mm x 0.5
0603	0.063" x 0.031"	1.6 x 0.8
0805	0.08" x 0.05"	2.0 x 1.25
1206	0.126" x 0.063"	3.2 x 1.6
1210	0.12" x 0.10"	3.2 x 2.6
2020	0.20" x 0.20"	5.08 x 5.08
2512	0.25" x 0.12"	6.35 x 3.0

Transistor & Diode packages

1. SOT-23 Small outline transistor
2. SOD-123 - Small outline Diode

Integrated circuit SMD package

- Small outline integrated circuit (SOIC) - 1.27mm
- TSOP (thin small outline package)
- QFP (Quad Flat Pack)
- QFN (Quad Flat Non-leaded Pack)
- PLCC (Plastic Leaded Chip Carriers)
- PGA (Pin Grid Array)
- BGA (Ball Grid Array)

DIP
1 pin to another pin distance = 2.54mm
in through hole (18) breadboard

Electronic components

- Basics of components (Active & Passive)
 - Types of components.
- (consumes produce some external voltage).
- Active - depending on external source/voltage
- Passive not depending not (does not consume any external source voltage or current).

Mounting technologies

1. Through Hole technology
2. SMT technology.

2
size of PCB ↓
complexity ↓
cost ↓

Passive component SMC

Passive two terminal compon.

Package Type	Size
0201	0.024" x 0.024"
0402	0.04" x 0.04"
0603	0.063" x 0.063"
0805	0.08" x 0.08"
1206	0.125" x 0.125"
1210	0.12" x 0.12"
2020	0.20" x 0.20"
2512	0.25" x 0.25"

Transistor & Diode

1. SOT-23
2. SOD-123

Integrated circuit

- SMD outline I
- TSOP (thin small outline package)
- QFP (Quad Flat Pack)
- QFN (Quad Flat No Lead)
- PLCC (plastic lead chip carrier)
- PGA (Pin Grid Array)
- BGA (Ball Grid Array)

DIP
1 pin to another pin distance in through hole @ 1.27 mm

PC

what is PCB?

its importance?

PCB designing (next 3 days)

Agende

- Basic of electronic component type.